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Material Design and Process Development of Electrostatically Patterning Silver Capsuled Composite Particle for Preparing Conductive Tracks on Flexible Substrate

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Abstract

In this work, a silver-capsuled composite particle at micro-size has been facilely developed for electrostatic patterning of copper layers on flexible substrates, with high performance across manufacturing scalability, printing resolution and speed, and production affordability to end users. Herein, we launched a capping method for designing the particle as decorated with PVP capped silver ion as catalytic precursor all

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